



SSC8122GS8

N-Channel Enhancement Mode MOSFET

➤ Features

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D	ESD
20V	$\pm 8V$	220m Ω @4V5	1.2A	2K
		270m Ω @2V5		
		340m Ω @1V8		

➤ Description

This device is a N-Channel enhancement mode MOSFET which is produced with high cell density and DMOS trench technology. This device particularly suits low voltage applications, especially for battery powered circuits, the tiny and thin outline saves PCB consumption.

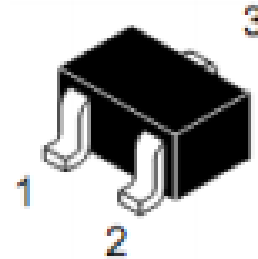
➤ Applications

- Replace Digital Transistor
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones

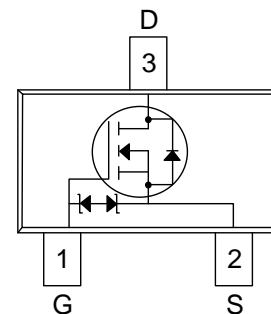
➤ Ordering Information

Device	Package	Shipping
SSC8122GS8	SOT-523	3000/Reel

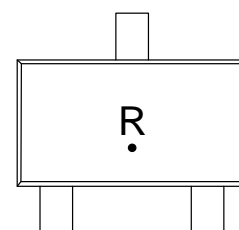
➤ Pin configuration



SOT-523



Pin Configuration (Top View)



Marking



➤ **Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
V_{DSS}	Drain-to-Source Voltage	20	V
V_{GSS}	Gate-to-Source Voltage	± 8	V
I_{D}	Continuous Drain Current ^a	1.2	A
I_{DM}	Pulsed Drain Current ^b	3.6	A
P_{D}	Power Dissipation ^c	0.37	W
P_{DSM}	Power Dissipation ^a	0.22	W
T_{J}	Operation junction temperature	-55~150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range	-55~150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter	Maximum	Unit
$R_{\theta\text{JA}}$	Junction-to-Ambient Thermal Resistance ^a	568	$^{\circ}\text{C}/\text{W}$
$R_{\theta\text{JC}}$	Junction-to-Case Thermal Resistance	340	$^{\circ}\text{C}/\text{W}$

Note:

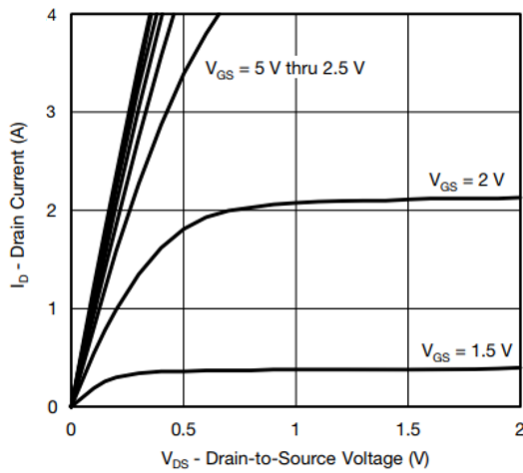
- The value of $R_{\theta\text{JA}}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user is specific board design. The power dissipation is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_{D} is based on $T_{\text{J(MAX)}}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

**➤ Electrical Characteristics (T_A=25°C unless otherwise noted)**

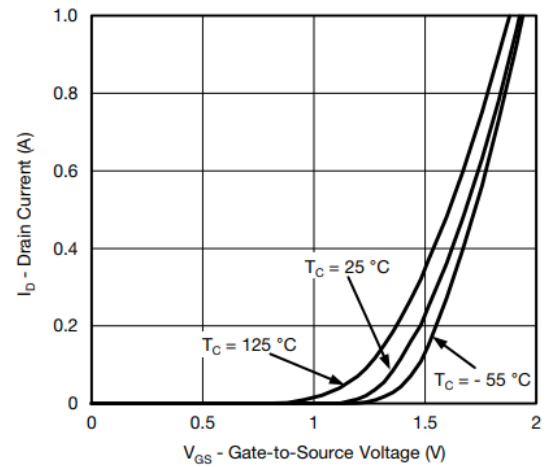
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	20			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	0.5	0.7	0.9	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D = 0.5A		220	400	mΩ
		V _{GS} = 2.5V, I _D = 0.5A		270	500	
		V _{GS} = 1.8V, I _D = 0.35A		340	800	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±8V, V _{DS} = 0V			±10	μA
Transconductance	G _{FS}	V _{DS} = 10V, I _D = 0.4A		1		s
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 0.5A			1.3	V
Input Capacitance	C _{ISS}	V _{DS} = 10V, V _{GS} = 0V, f = 100kHz		88		pF
Output Capacitance	C _{OSS}			17		
Reverse Transfer Capacitance	C _{RSS}			9		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = 4.5V, R _G = 6Ω		22		ns
Turn-off Delay Time	T _{D(OFF)}	V _{DD} = 10V, I _D = 0.55A		36		



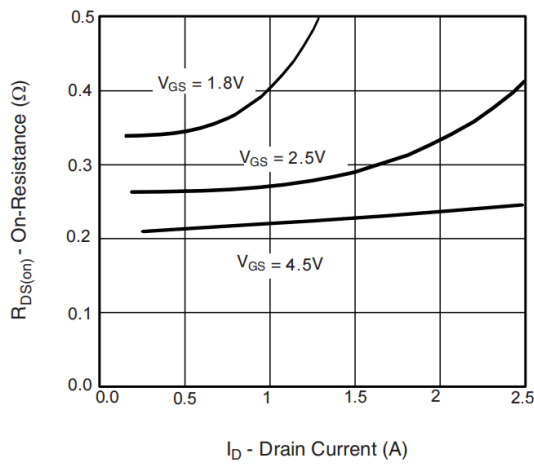
➤ Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



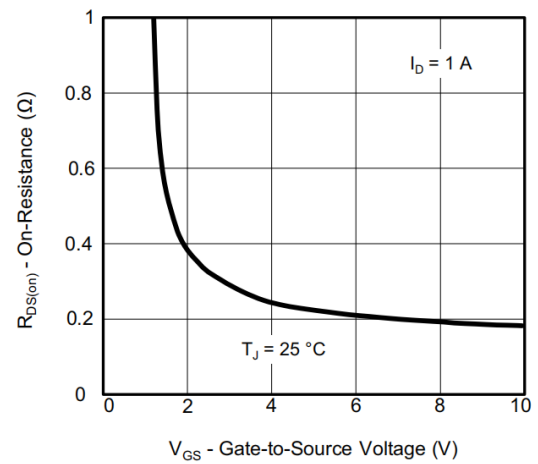
Output Characteristics



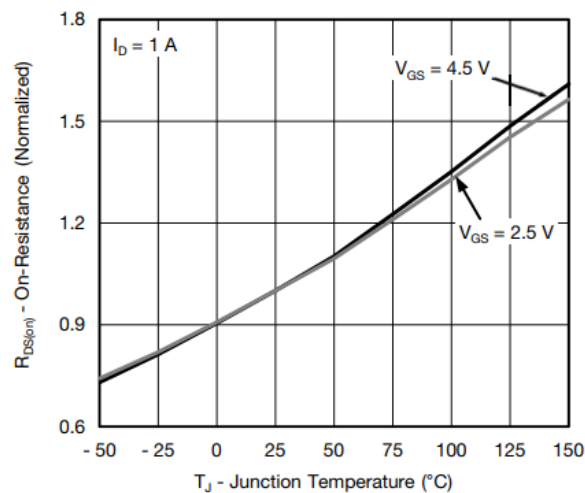
Transfer Characteristics



On-Resistance vs. Drain Current and Gate Voltage



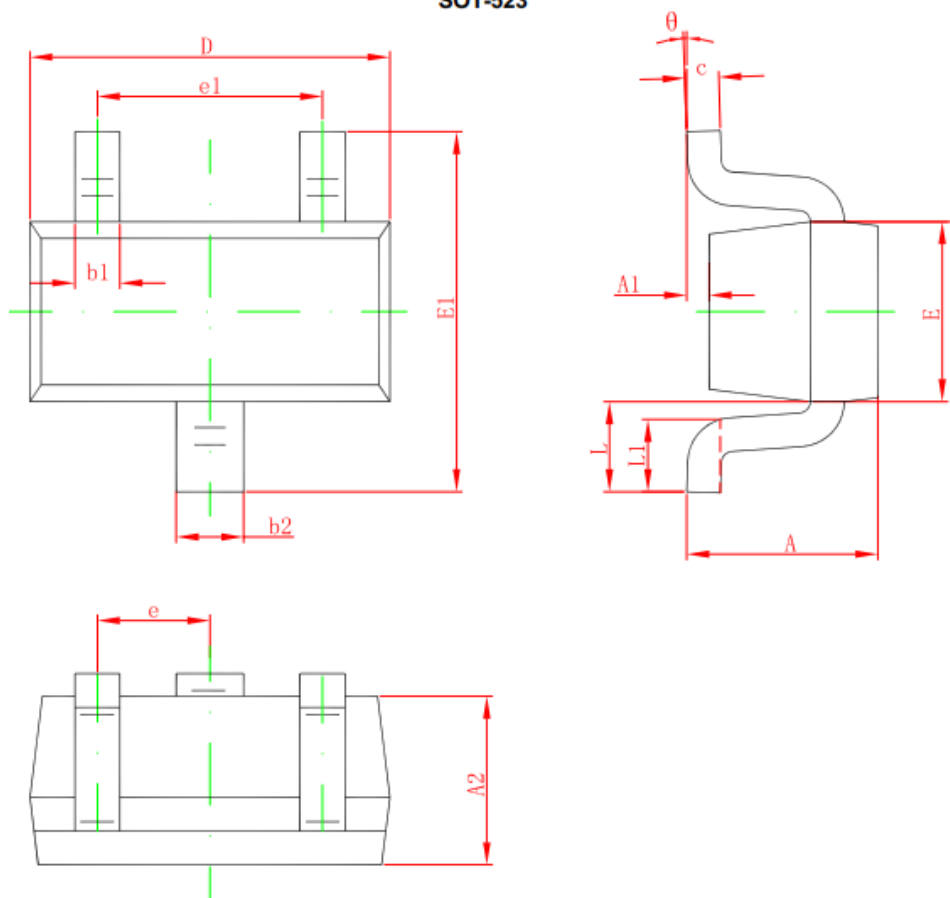
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature

➤ Package Information

SOT-523



Symbol	Dimension in Millimeters	
	Min.	Max.
A	0.700	0.900
A1	0.000	0.100
A2	0.700	0.800
b1	0.150	0.250
b2	0.250	0.350
c	0.100	0.200
D	1.500	1.700
E	0.700	0.900
E1	1.450	1.750
e	0.500 Typ.	
e1	0.900	1.100
L	0.400 Ref.	
L1	0.260	0.460
θ	0°	8°



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